Datacon's new 2200 evo die bonder:
The future of advanced packaging today

The 2200 evo is an evolutionary development. We kept all the proven features of the 2200 platform: modular machine concept, SEMI standard interface, highest accuracy of 10µm @ 3s, smallest footprint and an uptime of better than 98 percent. The operation of the 2200 evo is as easy as it is with all machines of our 2200 family, but we packed a lot of revolutionary features into it, which define the future of advanced packaging today.

Our brand new Twin-Head Multi-Chip Die Bonder offers you two machines in just one compact module: a separate dispensing area with integrated dispenser and a bonding area for die attach and flip chip applications. Furthermore, the 2200 evo handles 300mm wafer magazines inside the machine on less than 1.5 square meters. The amazing performance of up to 7,000 UPH and a yield > 99.95 percent guarantee lowest cost of ownership and make Datacon's 2200 evo your ideal bonder for high end die attach applications like LEDs, Hybrids, SiPs, CMOS applications, Stacked Die applications or Power Devices.

Applications

Die attach

Flip chip

Hybrid/MCM

SiP - System in package

Stacked die

Thin Die

VisionPak®

With the globally unique platform concept up to 4 axis systems (dispensing and bonding) can be arranged consecutively to a single machine - UPH can be optionally multiplied.

- **Multi-chip module** - Flip chip and die attach tasks can be executed in just one module
- **Small footprint** - 2200 evo only requires 1,4 m2 of (clean room) floor space

- **Key specifications** Die handling from 0,17 mm - 50 mm, Placement accuracy of ±10 μm @ 3s (cmk = 1,33)
- **Operator friendly** - Despite the wide range of fittings and set-up options, operation of the 2200 evo is easy to learn - just as used for the 2200 platform. Data transfer via TCP/IP networks is naturally implemented, and the user interface is menu-driven.
- **Flexibility** - Even the standard module of the 2200 evo die bonders can be very variably equipped.
- **Extended epoxy features** - Next to flux film application via slide fluxer an (optionally) integrated dispense axis enables parallel dispensing and bonding in just one module with significant UPH increases for a multitude of different applications.
- **Heated options** - Heated bond head (up to 350 °C) and substrate heating (up to 150 °C) are available to cover today's and tomorrow's demands of heat-requiring applications.